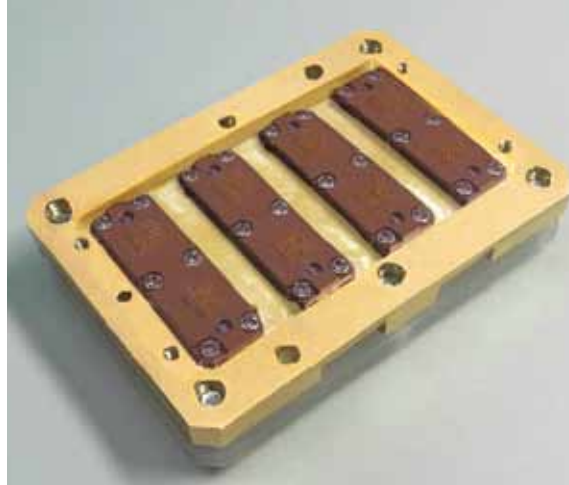
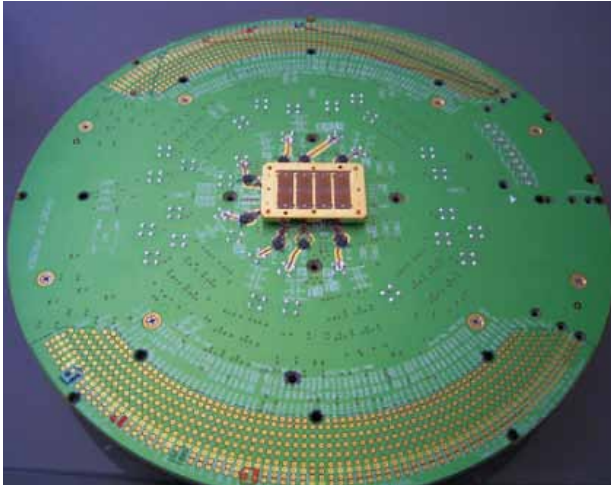


Yokowo Vertical High-Giga Probe Card (Hi-Speed) (YVH series)

yokowo



Yokowo Vertical High-Giga Probe Card

Applications

- Vertical probe design is available for area array electrode layout, which pitch size is more than 160 μ m.

Features

- A stable contact by the probe contactor method.
- Superior signal integrity up to 12GHz.
- Providing Appropriate pattern design by simulation in the electromagnetic field.
- Hand test for characterization capable by same contactor, therefore correlation data can be utilized for wafer test.
- Lower cost Compared to the current probecard contact method.
- Contact Probe can be replaced one by one.
- Available for area array.
- Multi-site parallel test capability.

Specification

Pitch	0.5mm	0.4mm	0.3mm	0.2mm	0.16mm
Insertion Loss@-1dB	8GHz	8GHz	5GHz	4GHz	4GHz
Return Loss@-10dB	12GHz	12GHz	6GHz	6GHz	6GHz
Crosstalk@-25db	6GHz	6GHz	TBD※	TBD※	TBD※
Contact Resistance	100m Ω	150m Ω	300m Ω	600m Ω	700m Ω
Current Carrying Capability	1.0A	0.6A	0.4A	0.3A	0.2A
Pin Force	25g	20g	6g	5g	5g
Over Drive	350 μ m	350 μ m	250 μ m	200 μ m	200 μ m
Max. Pin Count / DUT	250pln	250pln	250pln	250pln	250pln

※To Be Determined